MC74AC652, MC74ACT652

Octal Transceiver/Register with 3-State Outputs (Non-Inverting)

The MC74AC/ACT652 consists of registered bus transceiver circuits, with outputs, D−type flip−flops and control circuitry providing multiplexed transmission of data directly from the input bus or from the internal storage registers. Data on the A or B bus will be loaded into the respective registers on the LOW−to−HIGH transition of the appropriate clock pin (CAB or CBA). The four fundamental data handling functions available are illustrated in Figures 1 to 4.

Features

- Independent Registers for A and B Buses
- Multiplexed Real−Time and Stored Data Transfers
- Choice of True and Inverting Data Paths
- 3−State Outputs
- 300 mil Slim Dual−in−Line Package
- Outputs Source/Sink 24 mA
- ′ACT652 Has TTL Compatible Inputs
- These are Pb−Free Devices

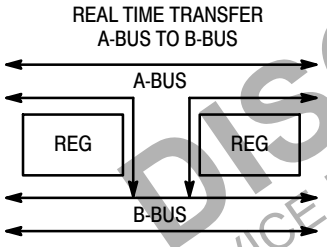

Figure 1.

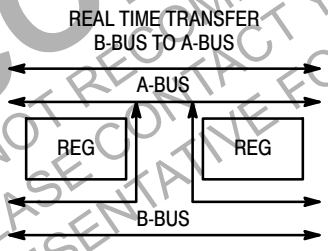

Figure 2.

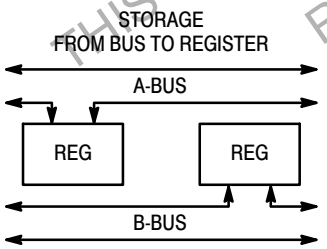

Figure 3.

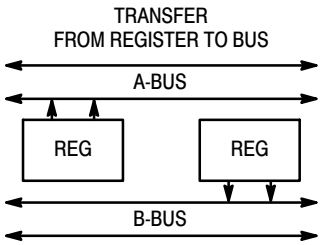

Figure 4.

ON Semiconductor™

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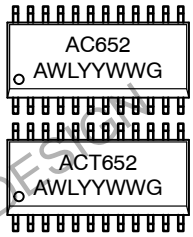
MARKING DIAGRAMS

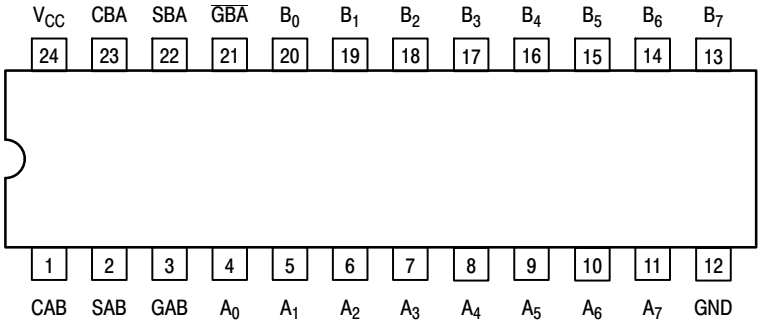
SO−24
DW SUFFIX
CASE 751E



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.



PIN ASSIGNMENT

PIN	FUNCTION
A_0–A_7	Data Register A Inputs Data Register A Outputs
B_0–B_7	Data Register B Inputs Data Register B Outputs
CAB, CBA	Clock Pulse Inputs
SAB, SBA	Transmit/Receive Inputs
GAB, $\overline{GBA}$	Output Enable Inputs

Figure 5. Pinout: 24−Lead Plastic Package
(Top View)

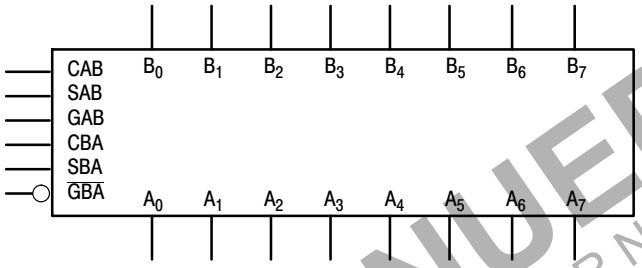
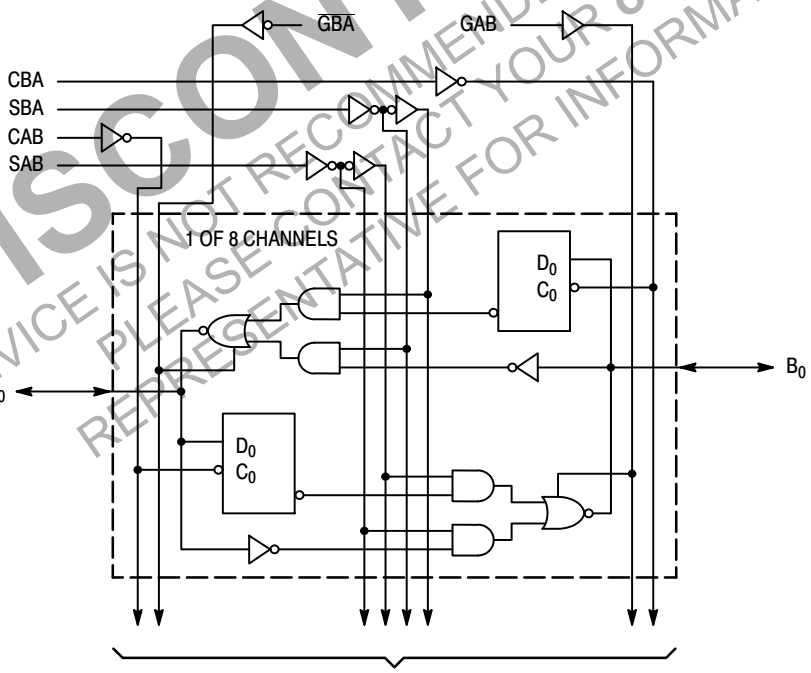


Figure 6. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 7. Logic Diagram

FUNCTION TABLE

Inputs						Data I/O*		Operation or Function
GAB	$\overline{GBA}$	CAB	CBA	SAB	SBA	$A_0 - A_7$	$B_0 - B_7$	
L L	H H	H or L ⇑	H or L ⇑	X X	X X	Input	Input	Isolation Store A and B Data
X H	H H	⇑ ⇑	H or L ⇑	X X**	X X	Input Input	Unspecified* Output	Store A, Hold B Store A in Both Registers
L L	X L	H or L ⇑	⇑ ⇑	X X	X X**	Unspecified* Output	Input Input	Hold A, Store B Store B in Both Registers
L L	L L	X X	X H or L	X X	L H	Output	Input	Real-Time B Data to A Bus Stored B Data to A Bus
H H	H H	X H or L	X X	L H	X X	Input	Output	Real-Time A Data to B Bus Stored A Data to B Bus
H	L	H or L	H or L	H	H	Output	Output	Stored A Data to B Bus and Stored B Data to A Bus

*The data output functions may be enabled or disabled by various signals at the $\overline{GBA}$ and GAB inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every LOW-to-HIGH transition of the appropriate clock inputs.
**Select control = L: clocks can occur simultaneously.
H = HIGH Voltage Level; L = LOW Voltage Level; X = Immaterial; ⇑ = LOW-to-HIGH Transition

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		−0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)		−0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND) (Note 1)		−0.5 to V_{CC} +0.5	V
I_{IK}	DC Input Diode Current		±20	mA
I_{OK}	DC Output Diode Current		±50	mA
I_{OUT}	DC Output Sink/Source Current		±50	mA
I_{CC}	DC Supply Current, per Output Pin		±50	mA
I_{GND}	DC Ground Current, per Output Pin		±100	mA
T_{STG}	Storage Temperature Range		− 65 to + 150	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		140	°C
θ_{JA}	Thermal Resistance (Note 2)		59.8	°C/W
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% − 35%	UL 94 V−0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
$I_{Latchup}$	Latchup Performance	Above V_{CC} and Below GND at 85°C (Note 6)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_{OUT} absolute maximum rating must be observed.
2. The package thermal impedance is calculated in accordance with JESD 51−7.
3. Tested to EIA/JESD22−A114−A.
4. Tested to EIA/JESD22−A115−A.
5. Tested to JESD22−C101−A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Min	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	−	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	−	150	−	ns/V
		V_{CC} @ 4.5 V	−	40	−	
		V_{CC} @ 5.5 V	−	25	−	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	−	10	−	ns/V
		V_{CC} @ 5.5 V	−	8.0	−	
T_A	Operating Ambient Temperature Range		−40	25	85	°C
I_{OH}	Output Current — HIGH		−	−	−24	mA
I_{OL}	Output Current — LOW		−	−	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = – 50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} – 12 mA I_{OH} – 24 mA – 24 mA
V_{OL}	Minimum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O= V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one input loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF		74AC T_A = −40°C to +85°C C_L = 50 pF		Unit
			Min	Max	Min	Max	
t_{PLH}	Propagation Delay CPBA or CPAB to A_n or B_n	3.0 5.0	4.0 2.5	17.0 12.0	3.0 2.0	19.0 14.0	ns
t_{PHL}	Propagation Delay CPBA or CPAB to A_n or B_n	3.0 5.0	3.0 2.0	14.5 10.5	2.5 1.5	16.5 12.0	ns
t_{PLH}	Propagation Delay A or B to B_n or A_n	3.0 5.0	3.0 2.0	14.0 9.5	2.5 1.5	16.0 11.0	ns
t_{PHL}	Propagation Delay A or B to B_n or A_n	3.0 5.0	2.5 1.5	13.0 9.0	2.0 1.0	15.0 10.5	ns
t_{PLH}	Propagation Delay SBA or SAB to A_n or B_n	3.0 5.0	3.0 2.5	14.0 10.0	2.5 2.0	16.0 11.5	ns
t_{PHL}	Propagation Delay SBA or SAB to A_n or B_n	3.0 5.0	2.5 2.0	13.5 10.0	2.0 1.5	15.5 11.5	ns
t_{PZH}	Output Enable Time $\overline{OEBA}$ to A_n	3.0 5.0	2.5 1.5	12.0 9.0	2.0 1.0	13.5 10.0	ns
t_{PZL}	Output Enable Time $\overline{OEBA}$ to A_n	3.0 5.0	2.5 1.5	12.0 9.0	2.0 1.0	14.0 10.5	ns
t_{PHZ}	Output Disable Time $\overline{OEBA}$ to A_n	3.0 5.0	3.0 2.0	13.0 11.0	2.5 1.5	14.0 12.0	ns
t_{PLZ}	Output Disable Time $\overline{OEBA}$ to A_n	3.0 5.0	2.5 2.0	12.5 10.5	2.0 1.5	14.0 12.0	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA I_{OH} – 24 mA
V_{OL}	Minimum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA I_{OH} – 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one input loaded at a time.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = −40°C to +85°C C_L = 50 pF		Unit
			Min	Max	Min	Max	
t_{PLH}	Propagation Delay CPBA or CPAB to A_n or B_n	5.0	4.0	14.5	3.5	16.5	ns
t_{PHL}	Propagation Delay CPBA or CPAB to A_n or B_n	5.0	3.5	14.5	3.0	16.5	ns
t_{PLH}	Propagation Delay A or B to B_n or A_n	5.0	2.5	11.5	2.0	13.0	ns
t_{PHL}	Propagation Delay A or B to B_n or A_n	5.0	2.5	11.5	2.0	13.0	ns
t_{PLH}	Propagation Delay SBA or SAB to A_n or B_n	5.0	2.5	12.0	2.0	13.5	ns
t_{PHL}	Propagation Delay SBA or SAB to A_n or B_n	5.0	3.0	12.0	2.5	13.5	ns
t_{PZH}	Output Enable Time $\overline{OEBA}$ to A_n	5.0	2.0	11.5	1.5	13.0	ns
t_{PZL}	Output Enable Time $\overline{OEBA}$ to A_n	5.0	2.5	11.5	2.0	13.0	ns
t_{PHZ}	Output Disable Time $\overline{OEBA}$ to A_n	5.0	3.0	13.0	2.5	14.0	ns
t_{PLZ}	Output Disable Time $\overline{OEBA}$ to A_n	5.0	2.5	12.5	2.0	14.0	ns
t_{PZH}	Output Enable time OEAB to B_n	5.0	2.5	12.0	2.0	13.5	ns
t_{PZL}	Output Enable Time OEAB to B_n	5.0	2.5	12.0	2.0	13.5	ns
t_{PHZ}	Output Enable Time OEAB to B_n	5.0	3.5	13.5	3.0	14.5	ns
t_{PLZ}	Output Enable Time OEAB to B_n	5.0	3.0	13.5	2.5	15.0	ns
t_s	Setup Time, HIGH or LOW A_n or B_n to CPBA or CPAB	5.0	7.0	–	8.0	–	ns
t_h	Hold Time, HIGH or LOW A_n or B_n to CPBA or CPAB	5.0	2.5	–	2.5	–	ns
t_w	CPAB, CPBA Pulse Width HIGH or LOW	5.0	6.0	–	7.0	–	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	74ACT Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
$C_{I/O}$	Input/Output Capacitance	15	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	60.0	pF	V_{CC} = 5.0 V

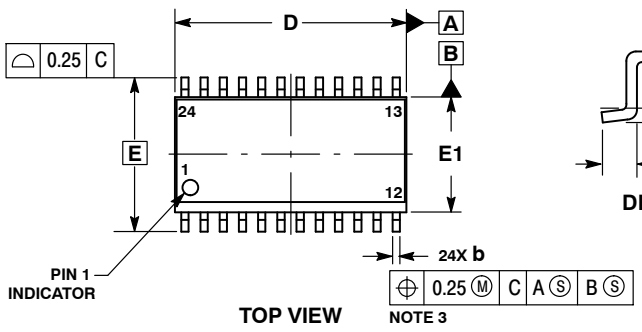
ORDERING INFORMATION

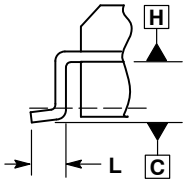
Device	Package	Shipping†
MC74AC652DWG	SOIC−24 (Pb−Free)	30 Units / Rail
MC74AC652DWR2G		1000 / Tape & Reel
MC74ACT652DWG		30 Units / Rail
MC74ACT652DWR2G		1000 / Tape & Reel

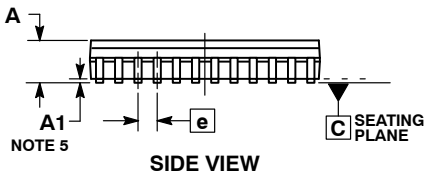
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

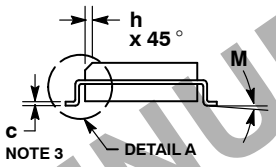
PACKAGE DIMENSIONS

SOIC−24 WB
DW SUFFIX
CASE 751E−04
ISSUE F





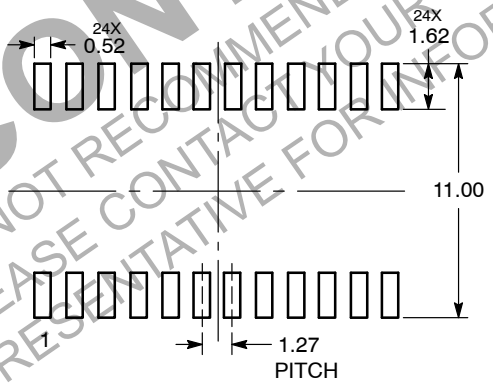




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD AND ARE MEASURED BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.13	0.29
b	0.35	0.49
c	0.23	0.32
D	15.25	15.54
E	10.30 BSC	
E1	7.40	7.60
e	1.27 BSC	
h	0.25	0.75
L	0.41	0.90
M	0 °	8 °

RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
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Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
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